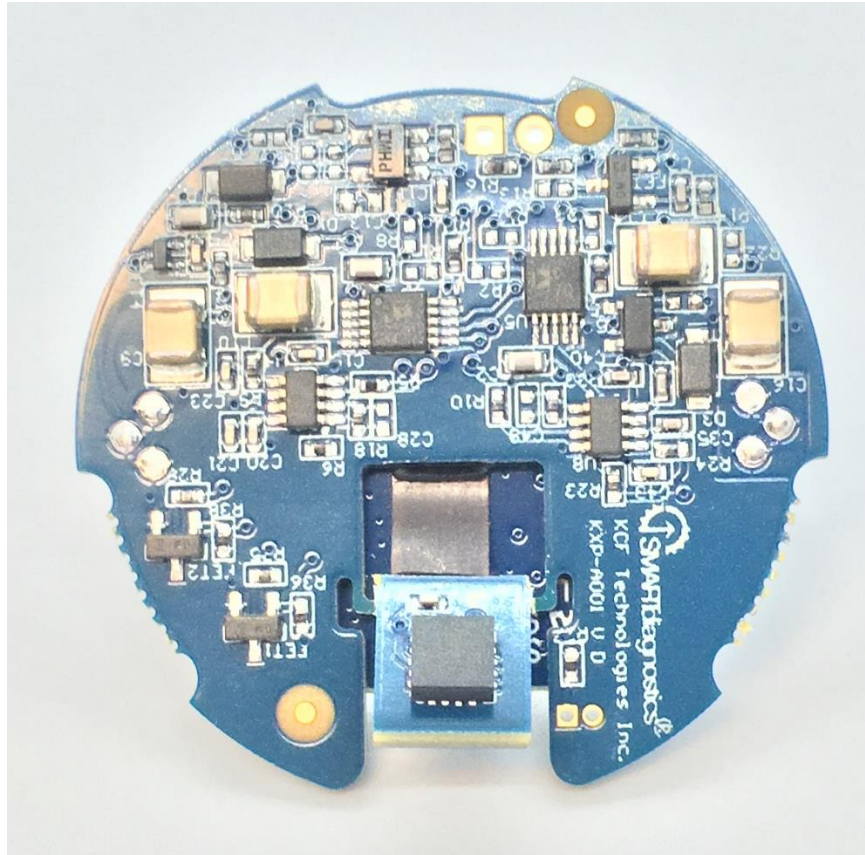
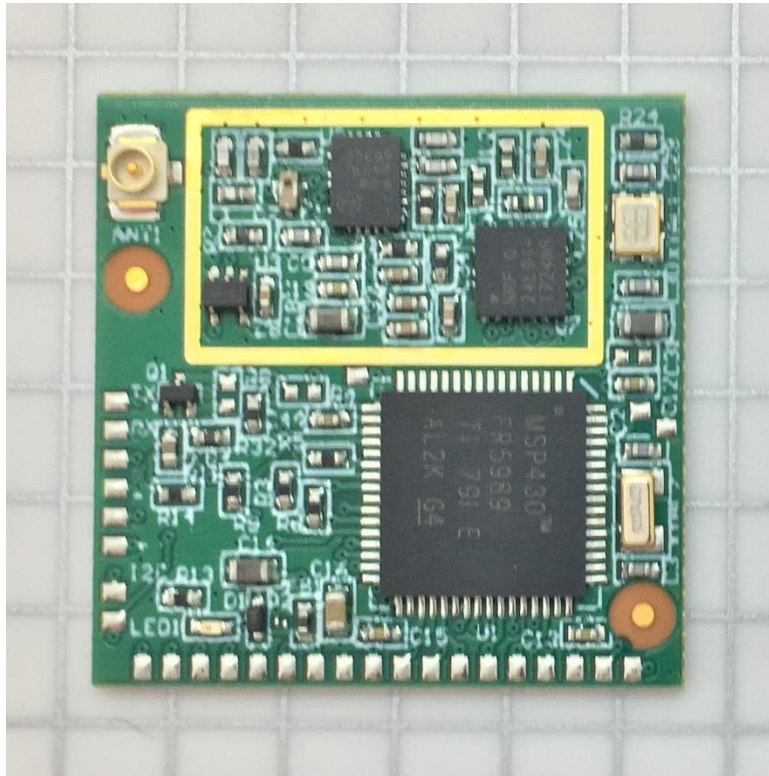


Top view of internal electronics assembly. The assembly consists of a “Wireless PCB” (square) containing the microcontroller, radio, and RF front-end, and a “Sensor PCB” (round) containing the sensor and signal conditioning. Grid pattern is 5mm.



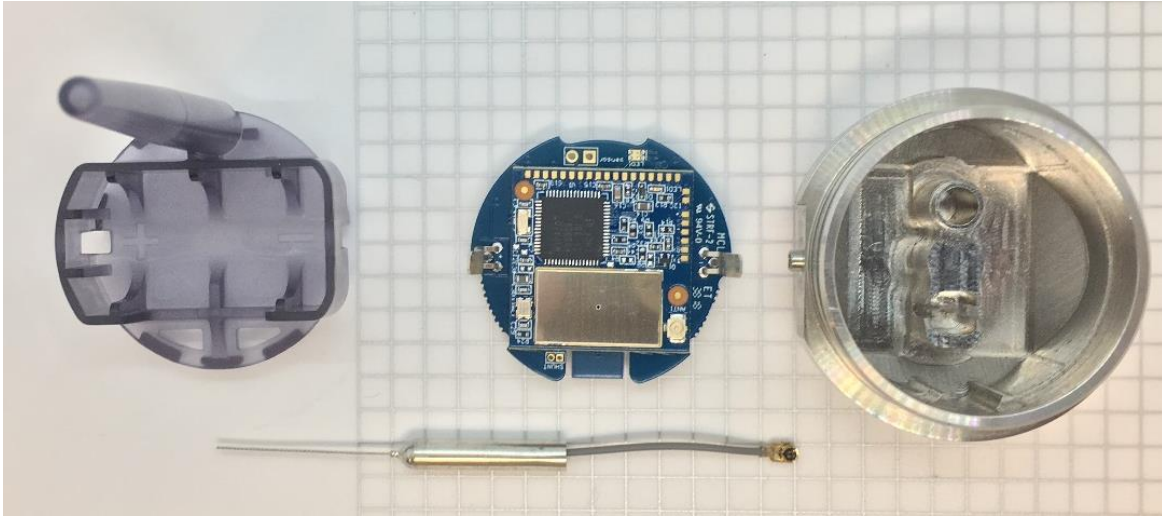
Bottom view of internal electronics assembly. The “Wireless PCB” can be seen through the cutout of the “Sensor PCB”.



Top view of “Wireless PCB” prior to attaching to “Sensor PCB”, without RF shield. Grid pattern is 5mm.



Bottom view of “Wireless PCB.” Grid pattern is 5mm.

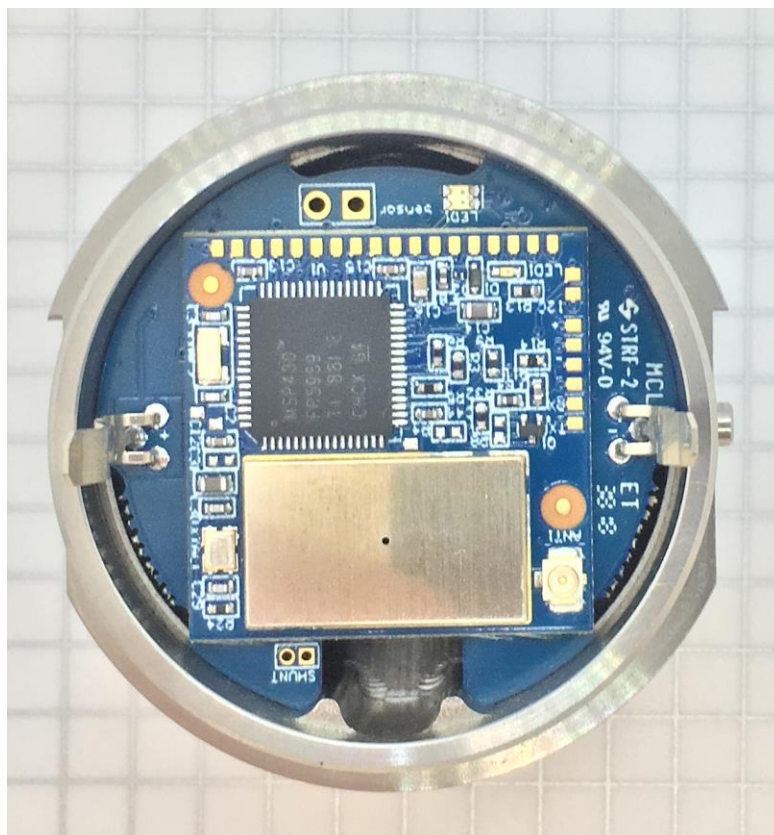


Housing components, electronics assembly, and antenna. The electronics are fully encapsulated during assembly.



Detail of lower section of housing. Material is stainless steel.





Electronics installed in lower section of housing.